

ABSTRACT

A method is disclosed for applying a plurality of caps to a plurality of microfabricated devices at the wafer stage. A wafer is provided having a plurality of microfabricated devices. The method requires forming a plurality of first hollow molded caps from a layer of thermoplastic material which is placed in a mold. The mold has first and second mold halves which are brought together to form the caps. Each cap has a central portion and a perimeter wall. The caps are formed first as an array of caps in the mold. Separated caps are applied simultaneously to one side of the wafer. The first caps are attached to the wafer, and then the wafer is then eventually separated into individual chips.